

Towards 1000x broadband amplification: A micromechanical amplifier for acoustic emission detection

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Motivation

High-sensitivity MEMS acoustic emission sensors are in general band-limited to a single resonance line [1,2]

Results		N4	N8
Measurements shown were performed on the			
out-of-plane moving structures with a Laser			

- \rightarrow disadvantageous when detecting weak, broadband environmental vibrations
- Broadband mechanical amplifier for vibration sensing is proposed



m_n

k₃≷

k₂≶

m₁ k₁≹

m₂

Concept

The mechanical amplifier consists of concentrically arranged kn≹ masses with following design constraints (i = 1, ..., n):

 $\frac{k_i + k_{i+1}}{2} = \omega_0$

 m_i

 $\frac{m_{i-1}}{2} = 2$ m_i

Weak vibrations exciting the outer-most mass and traveling towards the center mass are amplified, if they are within the allowed frequency band.



Doppler Vibrometer.



Average amplification



Transfer function



amplifica-Average tion at each mass of N4 and N8 is shown. 3-times higher Α amplification can be observed the at center mass for N8.

Transfer functions of the central masses of N4 and N8 are given. N8 shows a higher amplificaaverage tion over a broader normalized band-

Design approaches

Out-of-plane and in-plane moving structures have been designed and fabricated. The out-of-plane structures were made in SOI with the springs in the thin device layer and the in-plane structures in Si.

Out-of-plane



Optical microscope partial top view of out-of-plane device.

In-plane



Optical microscope partial Displacements of each mass of N8 are given. Indicent mechanical vibration is shoaled in a tsunafashion tomi-like the center wards mass.

Outlook

Process and design studies to increase the amplification up to 1000x are ongoing: As an example, such a design based on two functional substrate layers may achieve a baseline-amplification of 500.

Sensitive axis



Device layer Spring Bulk IU UM Tilted SEM image of a double

top view of in-plane device. 300 µm Tilted SEM image of serpentine spring.

References

- W. Wu, D. W. Greve, and I. J. Oppenheim, "Characterization and noise analysis of capacitive MEMS [1] acoustic emission transducers," in Proceeding of IEEE Sensors Conference, 2007, pp. 1152-1155.
- H. Saboonchi and D. Ozevin, "MEMS acoustic emission transducers designed with high aspect ratio [2] geometry," Smart Mater. Struct., vol. 22, no. 9, Sep. 2013.

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clamped beam (spring).







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